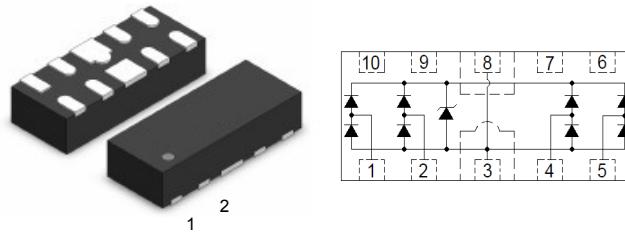


## Ultra Low Capacitance ESD TVS Array in DFN2510

### Features

- 30Watts peak pulse power ( $T_p = 8/20\mu s$ )
- DFN2510 Package
- Unidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance (0.15pF typical I/O to I/O)
- ESD Protection for high-speed data lines to:  
IEC 61000-4-2 ±8KV contact ±15KV air  
IEC 61000-4-4 (EFT) 40A (5/50ns)  
IEC 61000-4-5 (Lightning) 3A (8/20μs)



### Mechanical Data

- **Case:** DFN2510 (plastic package).  
Lead free; RoHS compliant; Halogen-free
- **Molding Compound Flammability Rating:**  
UL 94 V-0
- **Terminals:** High temperature soldering guaranteed:  
260 °C/10 sec. at terminals

### Applications

- USB 3.0, USB 2.0, MHL
- HDMI 2.0, Display Port 1.3, eSATA
- Unified Display Interface (UDI)
- Digital Visual Interface (DVI)
- High speed serial interfaces

### Absolute Maximum Ratings

Ratings at 25 °C, ambient temperature unless otherwise specified

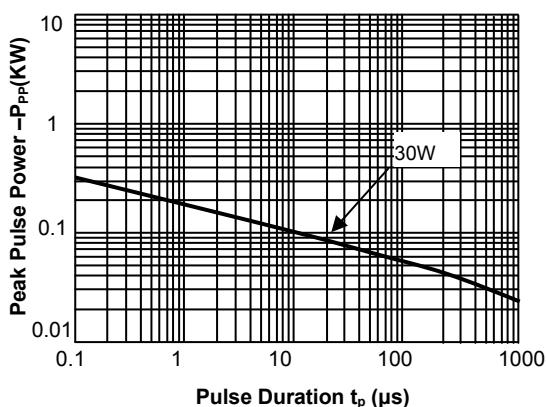
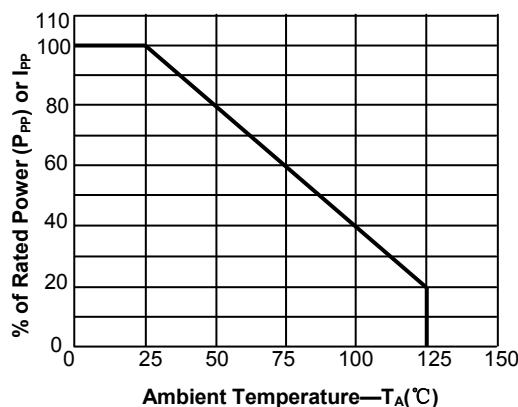
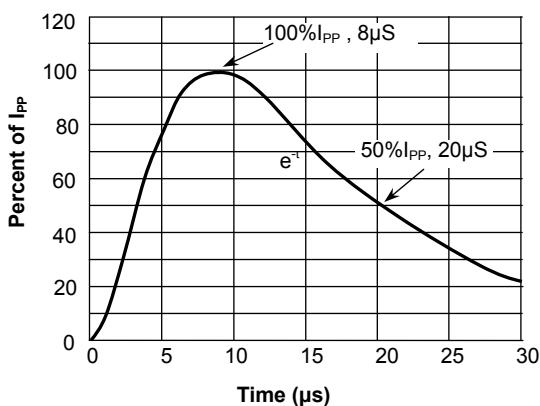
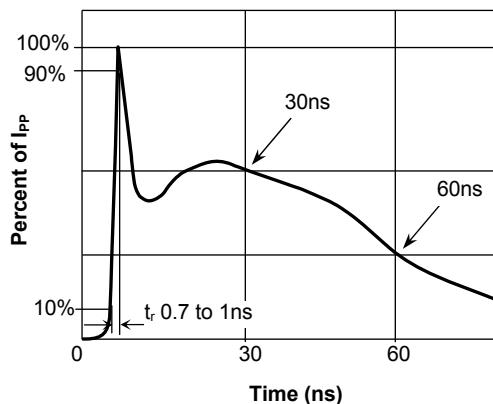
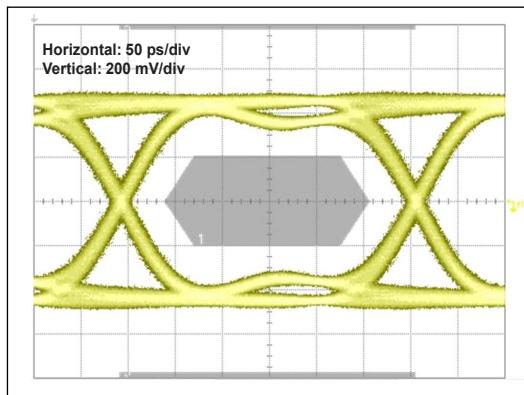
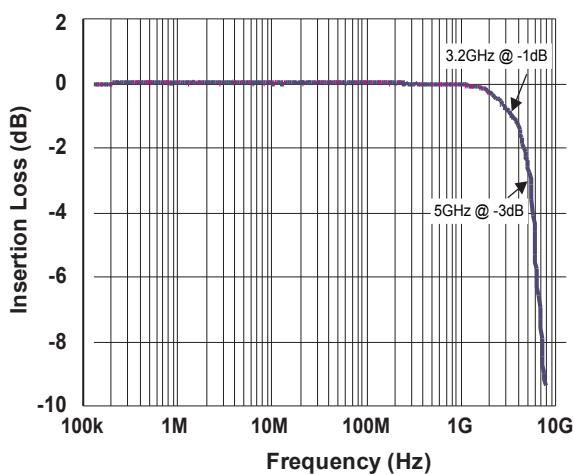
Parameter	Symbol	Value	Unit
Peak Pulse Power ( $T_p=8/20\mu s$ )	$P_{PP}$	30	W
ESD contact/air discharge (IEC-61000-4-2)	$V_{ESD}$	8/15	kV
Peak Pulse Current ( $t_p = 8/20\mu s$ )	$I_{PP}$	3.0	A
Junction Temperature	$T_J$	-55 to +125	°C
Storage temperature	$T_{STG}$	-55 to +150	°C

### Electrical Characteristics

( $T_A = 25$  °C unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Reverse stand-off Voltage	$V_{RWM}$				3.3	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1mA$	5	6.8		V
Reverse Leakage Current	$I_R$	$V_R=5V$			1	µA
Clamping Voltage(SURGE)	$V_C$	$I_{PP}=3A, T_p=8/20\mu s$		9		V
Clamping Voltage(ESD)	$V_C$	$V_{ESD} = +8kV$		9		V
Clamping Voltage(TLP)	$V_C$	$I_{PP}=16A, T_p=100ns$		9		V
Dynamic Resistance	$R_{dyn}$			0.25		Ω
Junction Capacitance	$C_J$	$V_R=0V, f=1MHz, I/O to I/O$		0.15		pF
	$C_J$	$V_R=0V, f=1MHz, I/O to GND$		0.35		pF

**Typical Characteristics** ( $T_{amb} = 25^{\circ}\text{C}$  unless otherwise specified)

**Fig.1 Peak Pulse Power Rating Curve**

**Fig.2 Pulse Derating Curve**

**Fig.3 Pulse Waveform-8/20μs**

**Fig.4 Pulse Waveform-ESD(IEC61000-4-2)**

**Fig.5 Eye Diagram - HDMI mask at 5Gbps per channel**

**Fig.6 Insertion Loss S21 - I/O to GND**


## Package Dimensions

Symbol	Dimensions in millimeters		
	Min	Nom	Max
A	0.45	0.50	0.55
A1		0.02	0.05
A3	0.10	0.15	0.20
D	2.45	2.50	2.55
E	0.95	1.00	1.05
D1	0.35	0.40	0.45
b	0.15	0.20	0.25
e	0.50BS		
L	0.35	0.40	0.45

## Pad Dimensions

Symbol	Dimension	
	Inches	millimeters
C	.034	0.875
G	.008	0.20
P	.020	0.50
P1	.039	1.00
X	.010	0.25
X1	.018	0.45
Y	.027	0.675
Y1	.061	1.55
Z	.061	1.55

## Package Information

Symbol	Typical	Unit
A0	1.15	
B0	2.65	
D	1.55	
P0	4.00	
P1	4.00	
P2	2.00	
E	1.75	
F	3.50	
W	8.00	

## Marking



## Ordering information

Order code	Package	Packaging option	Base quantity	Packaging specification
TESD2510UC3V3U	DFN2510	Tape and reel	3000pcs / reel	EIA STD RS-481